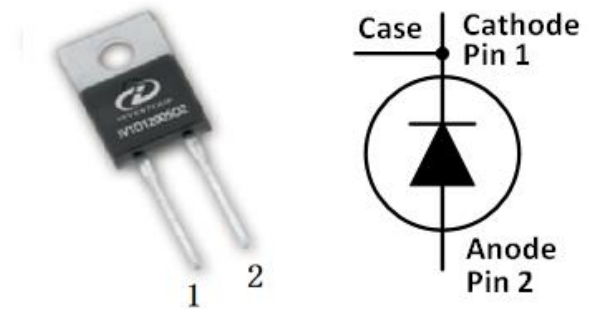


IV1D12005O2 – 1200V 5A SiC Schottky Diode

Features:

- Max Junction Temperature 175°C
- High Surge Current Capacity
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature independent switching behavior
- Positive Temperature Coefficient on V_F

Package



Applications:

- Solar Power Boost
- Inverter Free Wheeling Diodes
- Vienna 3-Phase PFC
- EV Charger Piles
- Switch Mode Power Supplies

Part Number	Package
IV1D12005O2	TO220-2

Absolute Maximum Ratings (Tc=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit
V_{RRM}	Reverse voltage (repetitive peak)	1200	V
V_{DC}	DC blocking voltage	1200	V
I_F	Forward current (continuous) @Tc=25°C	17	A
	Forward current (continuous) @Tc=155°C	5	A
I_{FSM}	Surge non-repetitive forward current sine halfwave @Tc=25°C tp=10ms	35	A
P_{tot}	Total power dissipation @ Tc=25°C	110	W
	Total power dissipation @ Tc=150°C	18	
$\int i^2 dt$	I^2t value @Tc=25°C tp=10ms	61	A ² S
Tstg	Storage temperature range	-55 to 175	°C
Tj	Operating junction temperature range	-55 to 175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Electrical Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V _F	Forward Voltage	1.52	1.8	V	I _F = 5 A T _J = 25°C	Fig. 1
		2.20	3.0		I _F = 5 A T _J = 175°C	
I _R	Reverse Current	2.5	30	μA	V _R = 1200 V T _J = 25°C	Fig. 2
		10	150		V _R = 1200 V T _J = 175°C	
C	Total Capacitance	320		pF	V _R = 1 V, T _J = 25°C, f = 1 MHz	Fig. 3
		32			V _R = 400 V, T _J = 25°C, f = 1 MHz	
		22			V _R = 800 V, T _J = 25°C, f = 1 MHz	
Q _C	Total Capacitive Charge	34		nC	V _R = 800 V, T _J = 25°C, $Q_C = \int_0^{V_R} C(V) dV$	Fig. 4

Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Note
R _{th(j-c)}	Thermal Resistance from Junction to Case	1.36	°C/W	Fig.7

Typical Performance

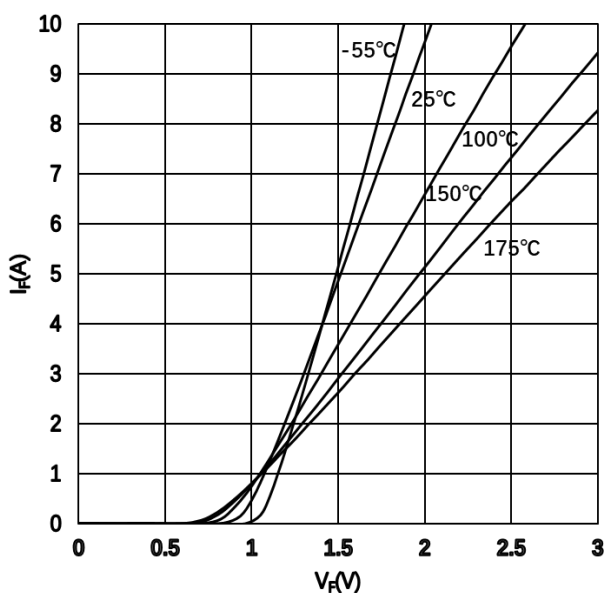


Figure 1. Typical Forward Characteristics

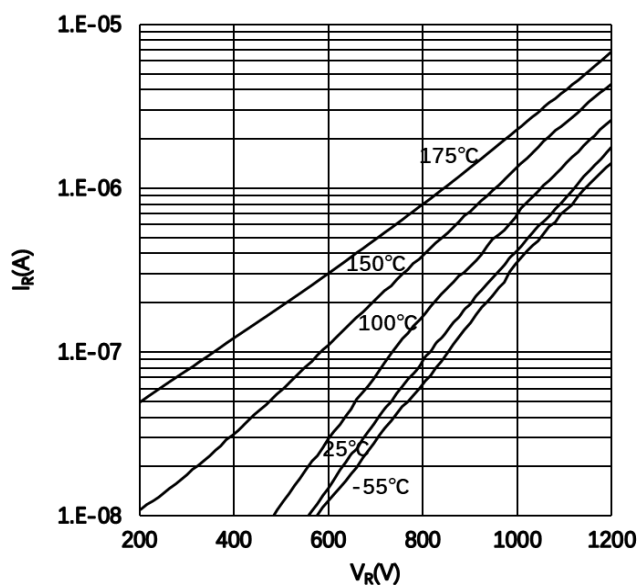


Figure 2. Typical Reverse Characteristics

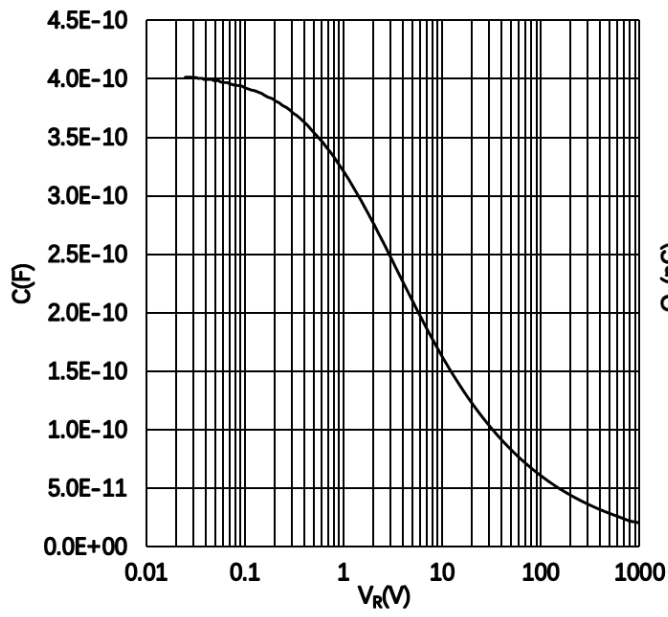


Figure 3. Capacitance vs. Reverse Voltage

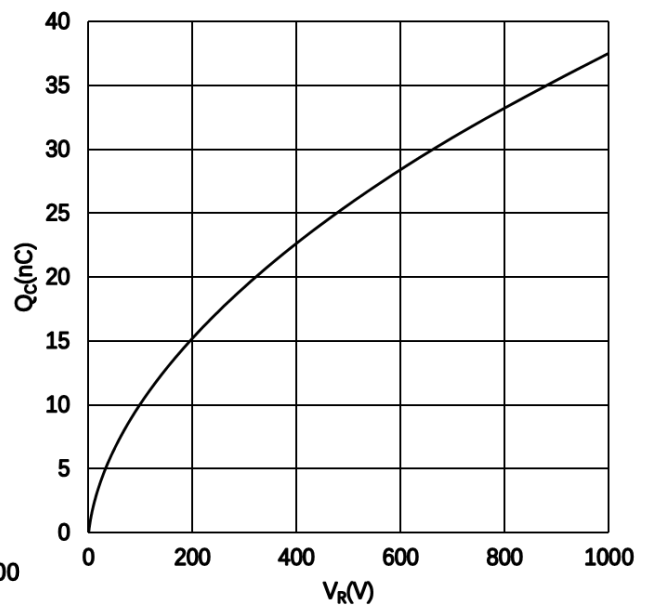


Figure 4. Recovery Charge vs. Reverse Voltage

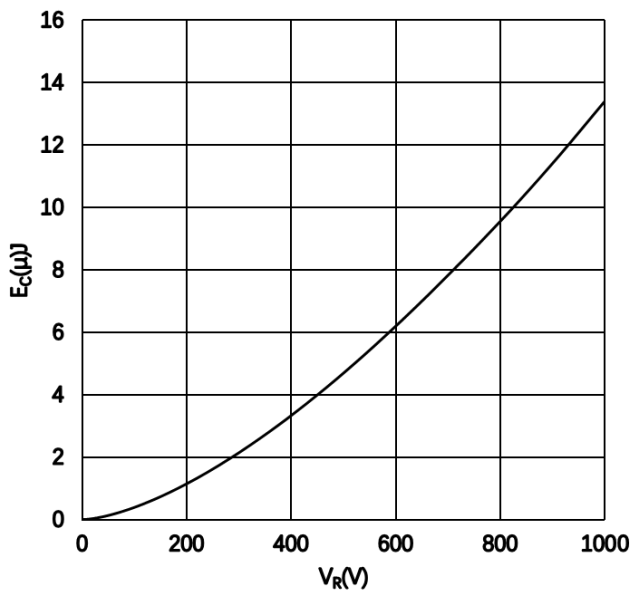


Figure 5. Capacitance Stored Energy

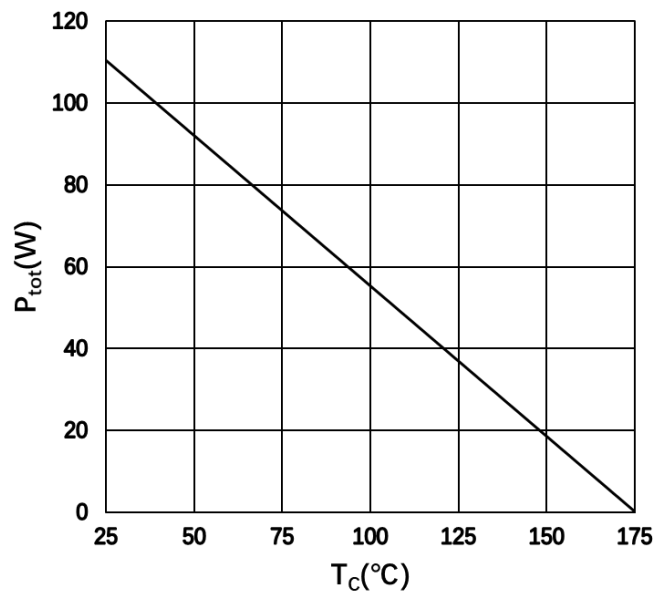


Figure 6. Power Derating

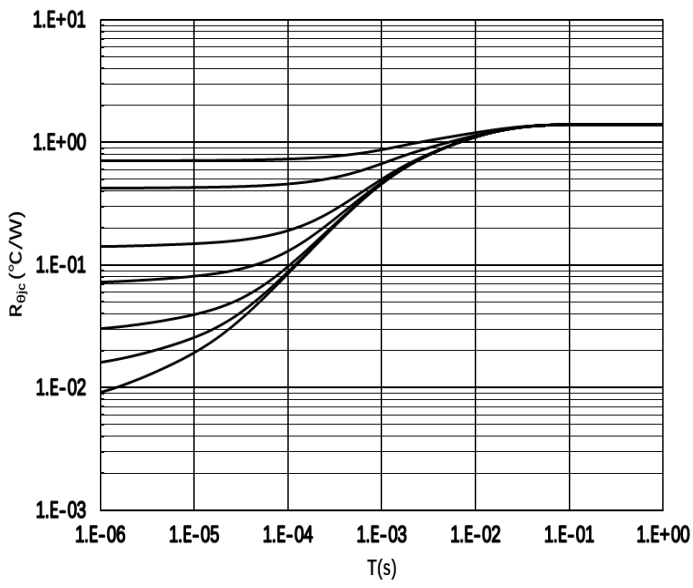


Figure 7. Transient Thermal Impedance

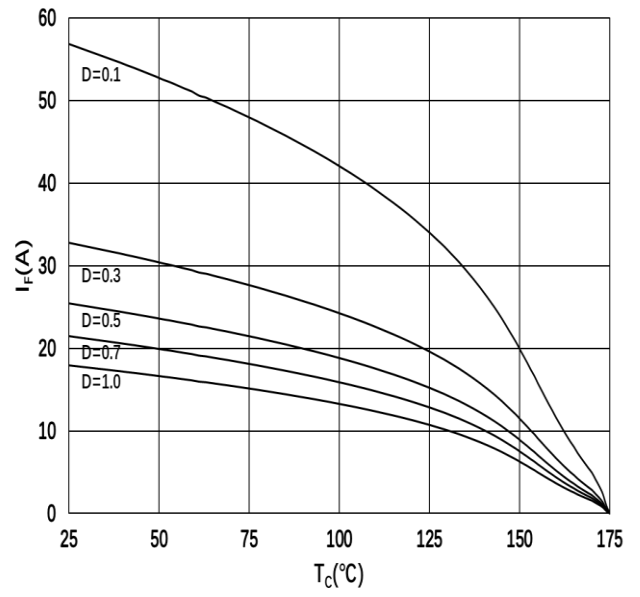
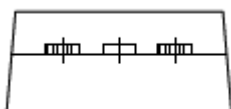
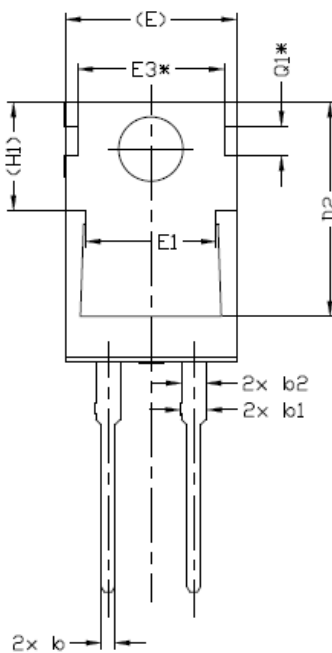
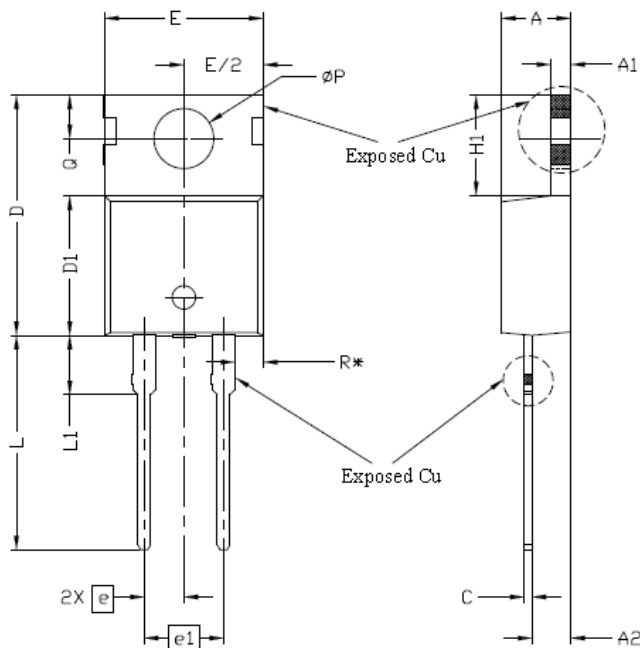


Figure 8. Forward Current as a Function of Temp.

Package Dimensions



SYMBOL	DIMENSIONS			NOTES
	MIN.	NOM.	MAX.	
A	4.24	4.44	4.64	
A1	1.15	1.27	1.40	
A2	2.30	2.48	2.70	
b	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
c	0.40	0.50	0.60	
D	14.70	15.37	16.00	4
D1	8.82	8.92	9.02	
D2	12.63	12.73	12.83	5
E	9.96	10.16	10.36	4,5
E1	6.86	7.77	8.89	5
E3*	8.70REF.			
e	2.54BSC			
e1	5.08BSC			
H1	6.30	6.45	6.60	5,6
L	13.47	13.72	13.97	
L1	3.60	3.80	4.00	
øP	3.75	3.84	3.93	
Q	2.60	2.80	3.00	
Q1*	1.73REF.			
R*	1.82REF.			

Note:

1. Package Reference: JEDEC TO220, Variation AB
2. All Dimensions Are In mm
3. Slot Required, Notch May Be Rounded
4. Dimension D&E Do Not Include Mold Flash

Notes

For further information please contact IVCT's Sales Office.

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